**AEC-Q101 Qualified** 

# 1.5V Drive Nch MOSFET

# RUR040N02FRA

### Structure

Silicon N-channel **MOSFET** 

### Features

- 1) 1.5V drive
- 2) Low On-resistance.
- 3) Built-in G-S Protection Diode.
- 4) Small Surface Mount Package (TSMT3).

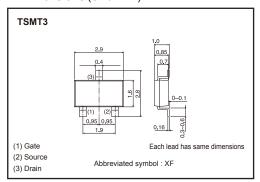
## Application

Switching

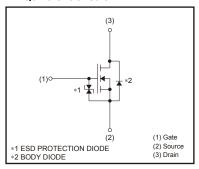
# Packaging specifications

	Package	Taping
Туре	Code	TL
	Basic ordering unit (pieces)	3000
RUR040N02	0	

### ●Dimensions (Unit: mm)



### ●Equivalent circuit



### ● Absolute maximum ratings (Ta=25°C)

Parameter		Symbol	Limits	Unit			
Drain-source voltage		V <sub>DSS</sub>	20	V			
Gate-source voltage		V <sub>GSS</sub>	±10	V			
Drain aurrant	Continuous	ID	±4.0	Α			
Drain current	Pulsed	I <sub>DP</sub> *1	±8.0	Α			
Source current	Continuous	Is	0.8	Α			
(Body diode)	Pulsed	I <sub>SP</sub> *1	8.0	Α			
Total power dissipation		P <sub>D</sub> *2	1.0	W			
Channel temperature		Tch	150	°C			
Range of storage temperature		Tstg	-55 to +150	°C			

<sup>\*1</sup> Pw≤10µs, Duty cycle≤1% \*2 Mounted on a ceramic board

# Thermal resistance

Parameter	Symbol	Limits	Unit	
Channel to ambient	Rth (ch-a)*	125	°C / W	

<sup>\*</sup> Mounted on a ceramic board

# ●Electrical characteristics (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions	
Gate-source leakage	Igss	-	_	±10	μΑ	V <sub>GS</sub> =±10V, V <sub>DS</sub> =0V	
Drain-source breakdown voltage	$V_{(BR)DSS}$	20	_	_	V	I <sub>D</sub> = 1mA, V <sub>GS</sub> =0V	
Zero gate voltage drain current	I <sub>DSS</sub>	-	-	1	μΑ	V <sub>DS</sub> =20V, V <sub>GS</sub> =0V	
Gate threshold voltage	V <sub>GS (th)</sub>	0.3	_	1.3	V	$V_{DS}$ = 10V, $I_D$ = 1mA	
		_	25	35	mΩ	I <sub>D</sub> =4.0A, V <sub>G</sub> s=4.5V	
Static drain-source on-state	D *	_	33	46	mΩ	I <sub>D</sub> =4.0A, V <sub>GS</sub> =2.5V	
resistance	R <sub>DS (on)</sub> *	_	42	59	mΩ	I <sub>D</sub> =2.0A, V <sub>GS</sub> =1.8V	
		-	55	110	mΩ	I <sub>D</sub> =0.8A, V <sub>GS</sub> =1.5V	
Forward transfer admittance	Y <sub>fs</sub> *	5.0	_	_	S	V <sub>DS</sub> = 10V, I <sub>D</sub> = 4.0A	
Input capacitance	Ciss	_	680	_	pF	V <sub>DS</sub> =10V	
Output capacitance	Coss	ı	150	_	pF	V <sub>GS</sub> =0V	
Reverse transfer capacitance	Crss	-	90	_	pF	f=1MHz	
Turn-on delay time	t <sub>d (on)</sub> *	_	10	_	ns	1 - 2 0 4 3 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4 4	
Rise time	tr *	-	30	_	ns	ID=2.0A, VDD≒ 10V VGS=4.5V	
Turn-off delay time	t <sub>d (off)</sub> *	ı	50	_	ns	V <sub>G</sub> S=4.3V R <sub>L</sub> ≒5Ω, R <sub>G</sub> =10Ω	
Fall time	t <sub>f</sub> *	-	60	_	ns		
Total gate charge	Q <sub>g</sub> *	_	8	_	nC	I <sub>D</sub> = 4.0A, V <sub>DD</sub> ≒ 10V	
Gate-source charge	Q <sub>gs</sub> *	_	1.8	_	nC	V <sub>GS</sub> =4.5V	
Gate-drain charge	Q <sub>gd</sub> *	_	1.3	_	nC	R <sub>L</sub> ≒2.5Ω, R <sub>G</sub> =10Ω	

<sup>\*</sup>Pulsed

# ●Body diode characteristics (Source-drain) (Ta=25°C)

Parameter	Symbol	Min.	Тур.	Max.	Unit	Conditions
Forward voltage	Vsp *	_	_	1.2	V	Is=0.8A, Vgs=0V

<sup>\*</sup>Pulsed

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#### Electrical characteristic curves

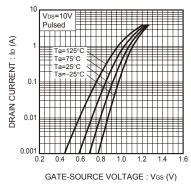


Fig.1 Typical Transfer Characteristics

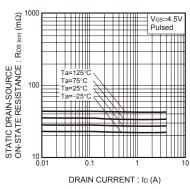


Fig.2 Static Drain-Source On-State Resistance vs. Drain Current (I)

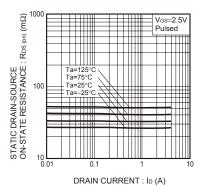


Fig.3 Static Drain-Source On-State Resistance vs. Drain Current (II)

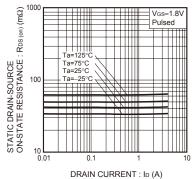


Fig.4 Static Drain-Source On-State Resistance vs. Drain Current (III)

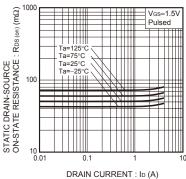


Fig.5 Static Drain-Source On-State Resistance vs. Drain Current (IV)

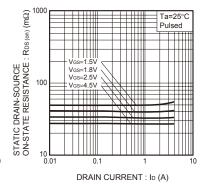


Fig.6 Static Drain-Source On-State Resistance vs. Drain Current (V)

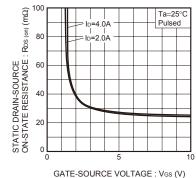


Fig.7 Static Drain-Source On-State Resistance vs. Gate-Source Voletage

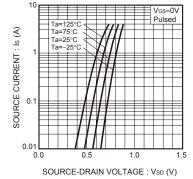


Fig.8 Source Current vs. Source-Drain Voltage

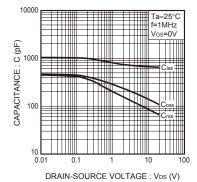
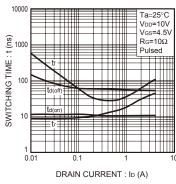
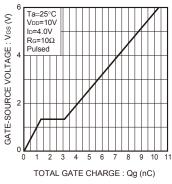


Fig.9 Typical Capacitance vs. Drain-Source Voltage





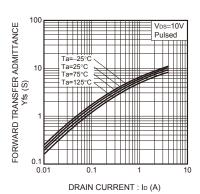


Fig.10 Switching Characteristics

Fig.11 Dynamic Input Characteristics

Fig.12 Forward Transfer
Admittance vs. Drain Current

### Measurement circuits

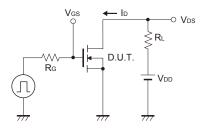


Fig.13 Switching Time Test Circuit

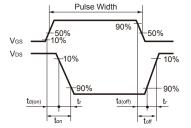


Fig.14 Switching Time Waveforms

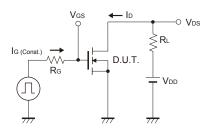


Fig.15 Gate Charge Test Circuit

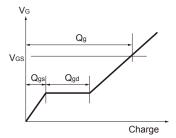


Fig.16 Gate Charge Waveform

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JAPAN	USA	CHINA		
CLASSⅢ	CL ACCIII	CLASS II b	CI VCCIII	
CLASSIV	CLASSⅢ	CLASSIII	CLASSII	

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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